



Material Content Data Sheet



Sales Product Name		BSL205N H6327		Issued		22. January 2018		
MA#		MA001165082						
Package		PG-TSOP6-6-4		Weight*		14.91 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	non noble metal	tin	7440-31-5	0.009	0.06		592	
	noble metal	gold	7440-57-5	0.034	0.23		2295	
	inorganic material	silicon	7440-21-3	0.522	3.50	3.79	35006	37893
leadframe	inorganic material	silicon	7440-21-3	0.001	0.01		95	
	non noble metal	titanium	7440-32-6	0.007	0.05		475	
	non noble metal	chromium	7440-47-3	0.021	0.14		1424	
	non noble metal	copper	7440-50-8	7.048	47.27	47.47	472685	474679
wire	non noble metal	copper	7440-50-8	0.139	0.93	0.93	9336	9336
encapsulation	organic material	carbon black	1333-86-4	0.066	0.44		4418	
	plastics	epoxy resin	-	1.416	9.50		94987	
	inorganic material	silicondioxide	60676-86-0	5.105	34.24	44.18	342394	441799
leadfinish	non noble metal	tin	7440-31-5	0.392	2.63	2.63	26323	26323
plating	noble metal	silver	7440-22-4	0.149	1.00	1.00	9970	9970
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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